

REMARKS

Claims 1 through 30 are currently pending in the application.

Claims 1 through 15 and 27 through 30 are withdrawn from consideration. Claims 16 through 26 are currently rejected.

This amendment is in response to the Office Action of October 28, 2003.

35 U.S.C. § 102(e) Anticipation Rejections

Anticipation Rejection Based on Kim et al. (U.S. Patent 6,225,688)

Claims 16 through 26 are rejected under 35 U.S.C. § 102(e) as being anticipated by Kim et al. (U.S. Patent 6,225,688).

Applicant asserts that a claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference.

Verdegaal Brothers v. Union Oil Co. of California, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

After carefully considering the cited prior art, the rejections, and the Examiner's comments, Applicant has amended the claimed invention to clearly distinguish over the cited prior art.

Applicant asserts that the Kim et al. reference does not and cannot anticipate the presently claimed invention of presently amended independent claims 16 and 23 because the Kim et al. reference does not identically describe, either expressly or inherently, each and every element as set forth in the presently amended claims in as complete detail as is contained in the claim.

For instance, the Kim et al. reference does not identically describe, either expressly or inherently, the elements of the presently claimed inventions calling for "providing at least one bare unpackaged semiconductor die having a plurality of bond pads on a first surface thereof" and "attaching said at least one semiconductor die to said flexible interposer forming an intermediate structure, said interposer being folded around said at least one bare unpackaged semiconductor die, said at least one bare unpackaged semiconductor die being in electrical communication with said substrate through a portion of the plurality of electrical contacts of said



Serial No. 09/813,724

flexible interposer by at least a portion of the plurality of electrical contacts filling at least portions of the plurality of vias extending from the first surface of the interposer to the second surface of the interposer contacting a plurality of bond pads on the first surface of the at least one bare unpackaged semiconductor die”.

Applicant asserts that, in contrast to the elements of the presently claimed invention of presently amended independent claims 16 and 23, the Kim et al. reference describes either a semiconductor die connected to leads 14 of the interposer 10 with leads 14 being connected to conductive vias 56 which are, in turn, connected to a substrate or semiconductor die 926 having connections 914 connected to terminals 922 extending through interposer 910 which are, in turn, connected to a substrate.

Therefore, presently amended independent claims 16 and 23 are allowable as well as dependent claims 17 through 22 and 24 through 26 therefrom.

Applicant submits that claims 16 through 26 are clearly allowable over the cited prior art.

Applicant requests the allowance of claims 16 through 26 and the case passed for issue.

Respectfully submitted,

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